

ABSTRACT

5 A pad cleaning device (210, 220, 250) is used in conjunction with spray rinse water to thoroughly clean a polishing pad (110) of a chemical-mechanical polishing system (100) after a wafer (120) has been polished. A sprayer or sprayer extension (210, 220, 250) is strategically positioned and securely retained on a portion of the dispensing arm (130) and adapted for applying a rinse water spray directly to the center portion (150) of the pad preventing conglomerated slurry from accumulating.